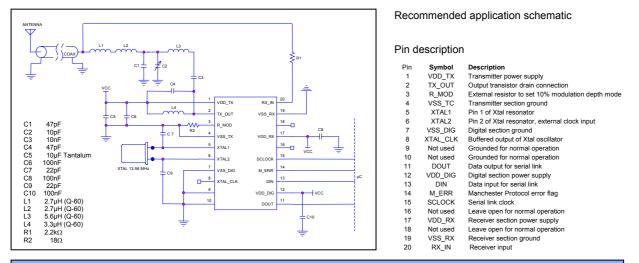


HF Reader System Series 6000 S6700 Multi-Protocol Transceiver IC

The S6700 Multi Protocol T ransceiver IC enables a broad range of 13.56MHz RFID interrogator designs for po rtable and stationary readers. This low power consumption device supports multiple RF communication protocols, minim izes onboard power requirements and reduces parts count in a final reader product.



Part number	RI-R6C-001A
Operating Frequency	13.56MHz
Supported RF Communication Protocols	 Tag-it HF ISO 15693-2 (e.g. Tag-it HF-I) ISO 14443-2 (Type A) Transparent (directly switched according to input pin)
Operating Voltage	$3.3V$ - 5V DC \pm 10%
Current Consumption	Transmit:< 200 mAStand-by: - Oscillator on< 15 mA
Transmitter power	200mW at 5V DC operating voltage
Transmitter modulation	ASK, 10% to 100% selectable through external components
Antenna Impedance	50 Ohm at 13.56MHz
Receive channels	ASK 423.75kHz, ASK 847kHz, FSK 423.75kHz/484.29kHz selectable
Communication Interface	Serial interface, CMOS compatible
Operating Temperature	-40°C to +85°C
Storage Temperature	-55°C to +125°C
Package / Pincount	SSOP 20
Packing / Delivery	Tape-on-Reel, 2000 units per reel



For more information, contact the sales office or distributor nearest you. This contact information can be found on our web site at: http://www.ti-rfid.com

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11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	e Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
RI-R6C-001A-03	ACTIVE	SSOP	DB	20	2000	TBD	Call TI	Call TI	-40 to 85		Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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